



BAS16HTW

Features

- Fast Switching Speed
- High Reverse Breakdown Voltage
- Low Leakage Current
- Low Capacitance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (<u>BAS16HTWQ</u>)

Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe. (Lead-Free Plating). Solderable per MIL-STD-202, Method 208⁽³⁾

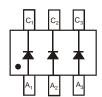
SURFACE MOUNT SWITCHING DIODE ARRAY

- Polarity: See Diagram
- Weight: 0.006 grams (Approximate)

SOT363



Top View



Top View Internal Schematic

Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging
BAS16HTW-13	AEC-Q101	SOT363	10,000/Tape & Reel
BAS16HTW-13R	AEC-Q101	SOT363	10,000/Tape & Reel

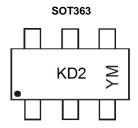
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. The "-13R" suffix indicates that the devices are rotated 180° in the carrier tape as compared with the standard "-13" suffix devices. For exact packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



KD2 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: C = 2015) M = Month (ex: 9 = September)

Date Code Key

Year	2015		2016	2017		2018	2019		2020	2021		2022
Code	С		D	E		F	G		Н	I		J
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} Vr	100	V	
RMS Reverse Voltage	V _{R(RMS)}	71	V	
Forward Continuous Current (Note 5)	IFM	200	mA	
Repetitive Peak Forward Current	I _{FRM}	500	mA	
	@ t = 1.0µs	I _{FSM}	4	
Non-Repetitive Peak Forward Surge Current	@ t = 1.0ms		1.0	А
	@ t = 1.0s		0.5	

Thermal Characteristics

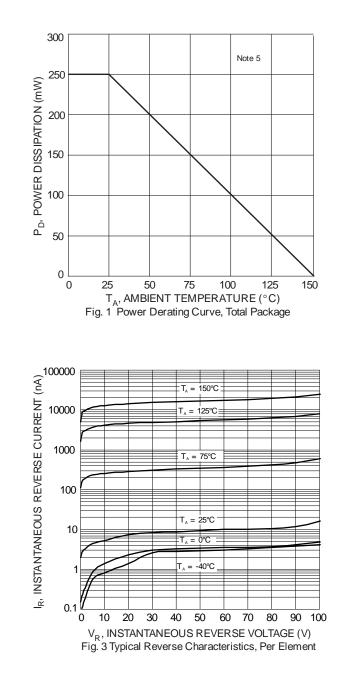
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	PD	250	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R _{θJA}	500	°C/W
Thermal Resistance Junction to Solder Point (Note 6)	R _{0JSP}	260	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

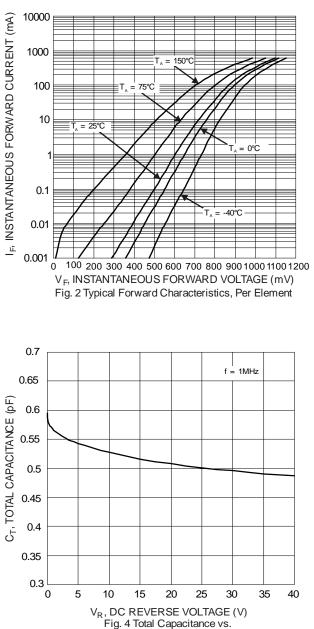
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)		100		V	I _R = 2.5μA
		_	0.715	v	I _F = 1.0mA
Forward Voltage	VF	_	0.855		I _F = 10mA
Forward voltage	VF	_	1.0		$I_F = 50 \text{mA}$
		_	1.25		I _F = 150mA
		_	0.5	μA	V _R = 80V
Reverse Current (Note 7)	1-	_	50		$V_R = 80V, T_J = +150^{\circ}C$
Reverse Guilent (Note 7)	I _R	_	30		$V_R = 25V, T_J = +150^{\circ}C$
		_	30	nA	$V_R = 25V$
Total Capacitance	CT	_	1.5	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t		4.0	ns	$I_F = I_R = 10 \text{mA},$
	t _{RR}				$I_{RR} = 0.1 \text{ x } I_{R}, R_{L} = 100\Omega$
Forward Recovery Voltage	V _{FR}	_	1.75	V	$I_F = 10mA; t_R = 20ns$

Notes: 5. Part mounted on FR-4 PC board with recommended pad layout, please see http://www.diodes.com/package-outlines.html for the latest version. 6. Soldering points at pins C_1 , C_2 and C_3 . 7. Short duration pulse test used to minimize self-heating effect.





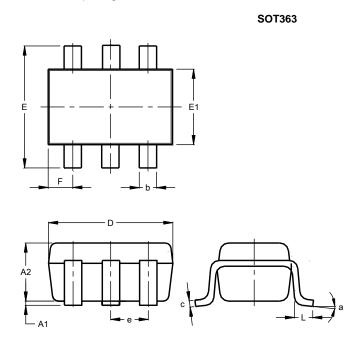


Reverse Voltage, Per Element



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

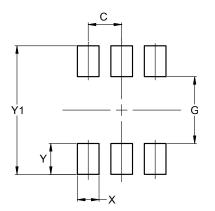


SOT363						
Dim	Min	Max	Тур			
A1	0.00	0.10	0.05			
A2	0.90	1.00	1.00			
b	0.10	0.30	0.25			
С	0.10	0.22	0.11			
D	1.80	2.20	2.15			
Е	2.00	2.20	2.10			
E1	1.15	1.35	1.30			
е	0.650 BSC					
F	0.40	0.45	0.425			
L	0.25	0.40	0.30			
а	0°	8°	-			
All	All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT363



Dimensions	Value (in mm)		
C	0.650		
G	1.300		
Х	0.420		
Y	0.600		
Y1	2.500		



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